

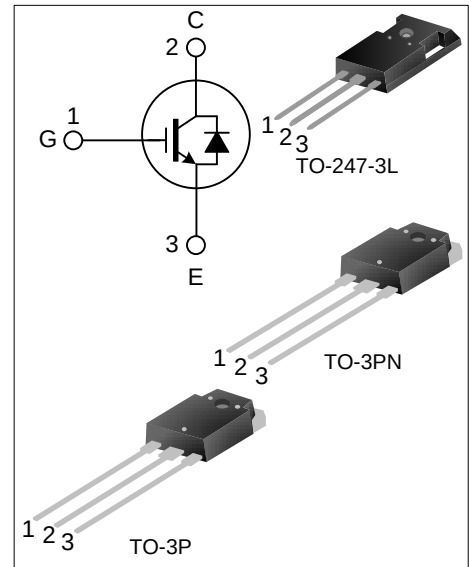
40A, 600V FIELD STOP IGBT

DESCRIPTION

SGT40N60FD2PN(P7)(PT) using Field Stop III IGBT technology, offers the optimum performance for induction Heating, UPS, SMPS and PFC application.

FEATURES

- 40A, 600V, $V_{CE(sat)}(typ.)=1.8V@I_C=40A$
- Low conduction loss
- Fast switching
- High input impedance



NOMENCLATURE

SGT 40 N 60 S D M 1 P7	
IGBT series	Package
Current, 40: 40A	P7 : TO-247-3L
N : N Channel	1,2,3... : Version No.
NE : N-channel planar gate with ESD	Blank: Standard diode
T : Field Stop 3/4	M : Standard Diode, full range
U : Field Stop 4+	R : Rapid Diode
V : Field Stop 5	B : Rapid Diode, full range
W : Field Stop 6	S : Soft Diode, full range
X : Field Stop 7	D : Packaged with fast recovery diode
Voltage, 65: 650V	R : RC IGBT
120: 1200V	L : Ultra low switching, recommended frequency ~2KHz
	Q : Low switching, recommended frequency 2~20K
	S : Standard frequency, recommended frequency 5~40K
	F : Fast switching, recommended frequency 10~60K
	UF : Ultra fast switching, recommended frequency 40K~

ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SGT40N60FD2PN	TO-3P	40N60FD2	Pb free	Tube
SGT40N60FD2P7	TO-247-3L	40N60FD2	Pb free	Tube
SGT40N60FD2PT	TO-3PN	40N60FD2	Pb free	Tube

ABSOLUTE MAXIMUM RATINGS (T_C=25°C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Ratings	Units
Collector to Emitter Voltage	V _{CE}	600	V
Gate to Emitter Voltage	V _{GE}	±20	V
Collector Current	I _C	T _C =25°C 80	A
		T _C =100°C 40	
Pulsed Collector Current	I _{CM}	120	A
Power Dissipation(T _C =25°C) -Derate above 25°C	P _D	380	W
		3.04	W/°C
Operating Junction Temperature Range	T _J	-55~+150	°C
Storage Temperature Range	T _{stg}	-55~+150	°C

THERMAL CHARACTERISTICS

Parameter	Symbol	Ratings	Units
Thermal Resistance, Junction to Case (IGBT)	R _{θJC}	0.33	°C/W
Thermal Resistance, Junction to Case (FRD)	R _{θJC}	1.9	°C/W
Thermal Resistance, Junction to Ambient	R _{θJA}	40	°C/W

ELECTRICAL CHARACTERISTICS OF IGBT ($T_C = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

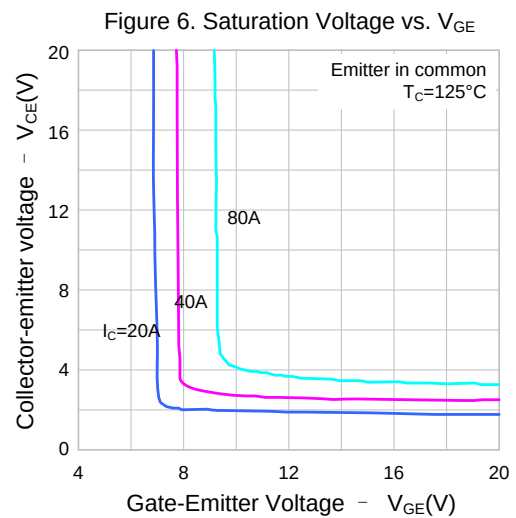
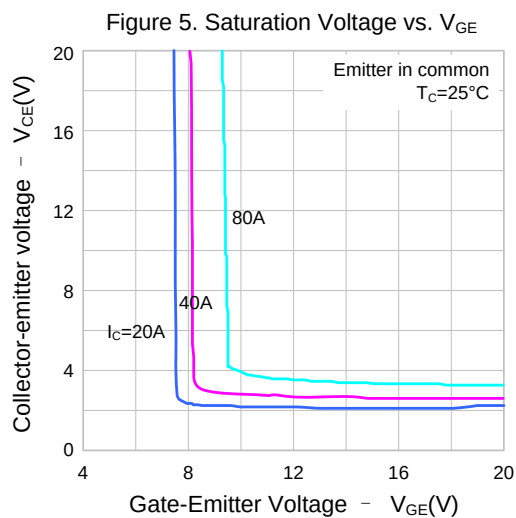
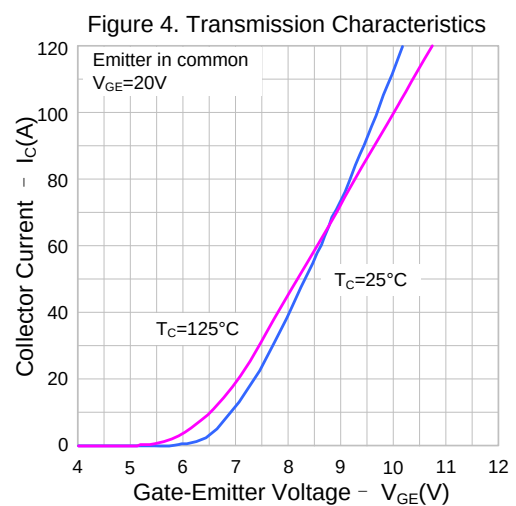
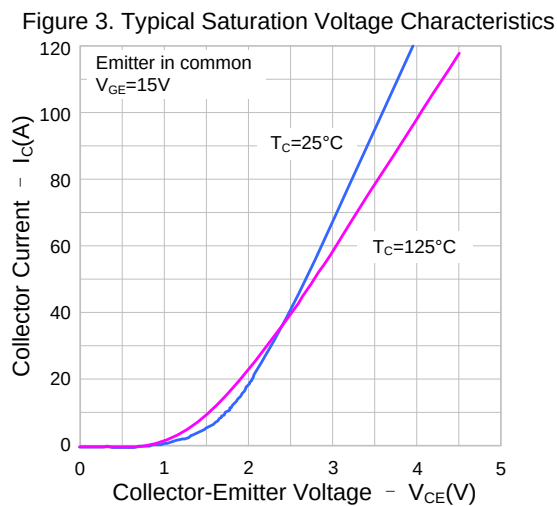
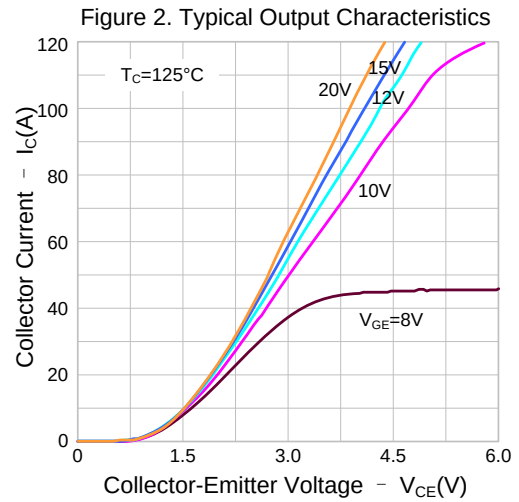
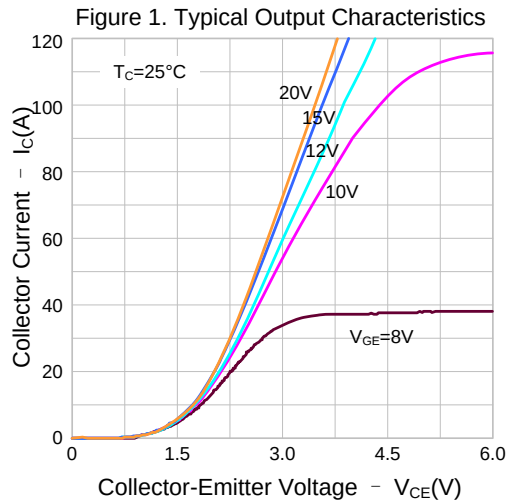
Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Units
Collector to Emitter Breakdown Voltage	BV_{CE}	$V_{GE}=0V, I_C=100\mu A$	600	--	--	V
C-E Leakage Current	I_{CES}	$V_{CE}=600V, V_{GE}=0V$	--	--	200	μA
G-E Leakage Current	I_{GES}	$V_{GE}=20V, V_{CE}=0V$	--	--	± 500	nA
G-E Threshold Voltage	$V_{GE(th)}$	$I_C=250\mu A, V_{CE}=V_{GE}$	4.0	5.0	6.5	V
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=40A, V_{GE}=15V$	--	1.8	2.7	V
		$I_C=40A, V_{GE}=15V, T_C=125^\circ\text{C}$	--	2.5	--	V
Input Capacitance	C_{ies}	$V_{CE}=30V$	--	1850	--	pF
Output Capacitance	C_{oes}	$V_{GE}=0V$	--	190	--	
Reverse Transfer Capacitance	C_{res}	$f=1\text{MHz}$	--	50	--	
Turn-On Delay Time	$T_{d(on)}$	$V_{CE}=400V$ $I_C=40A$ $R_g=10\Omega$	--	16	--	ns
Rise Time	T_r		--	88	--	
Turn-Off Delay Time	$T_{d(off)}$		--	110	--	
Fall Time	T_f		--	96	--	
Turn-On Switching Loss	E_{on}	$V_{GE}=15V$ Inductive Load	--	1.8	--	mJ
Turn-Off Switching Loss	E_{off}		--	0.8	--	
Total Switching Loss	E_{st}		--	2.6	--	
Total Gate Charge	Q_g	$V_{CE} = 300V, I_C=40A,$ $V_{GE} = 15V$	--	100	--	nC
Gate to Emitter Charge	Q_{ge}		--	11	--	
Gate to Collector Charge	Q_{gc}		--	52	--	

ELECTRICAL CHARACTERISTICS OF FRD ($T_C=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Units
Diode Forward Voltage	V_{FM}	$I_F = 20A, T_C=25^\circ\text{C}$	--	1.9	2.6	V
		$I_F = 20A, T_C=125^\circ\text{C}$	--	1.5	--	
Diode Reverse Recovery Time	T_{rr}	$I_{ES}=20A, di_{ES}/dt=200A/\mu s$	--	32	--	ns
Diode Reverse Recovery Charge	Q_{rr}	$I_{ES}=20A, di_{ES}/dt=200A/\mu s$	--	74	--	nC



TYPICAL CHARACTERISTIC CURVES





TYPICAL CHARACTERISTIC CURVES(CONTINUED)

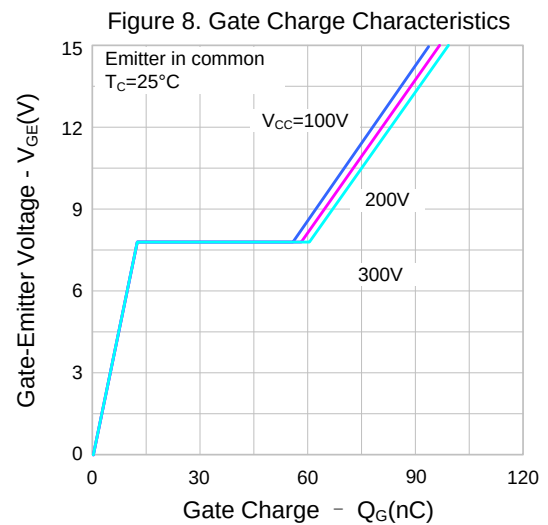
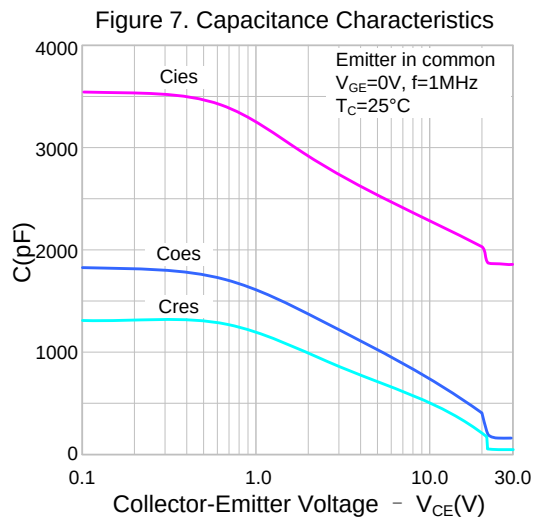


Figure 9. Turn-on Characteristics vs. Gate Resistance

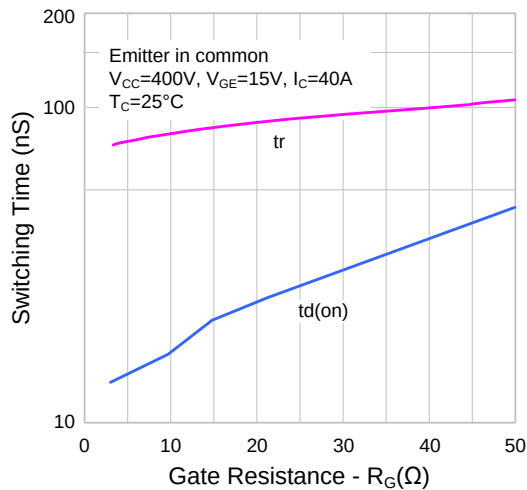


Figure 10. Turn-off Characteristics vs. Gate Resistance

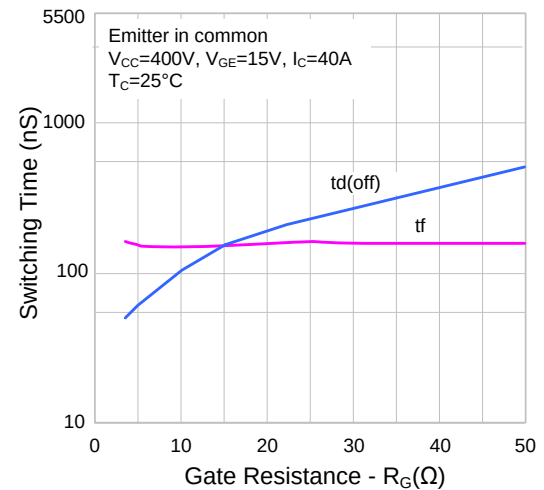


Figure 11. Switching Loss vs. Gate Resistance

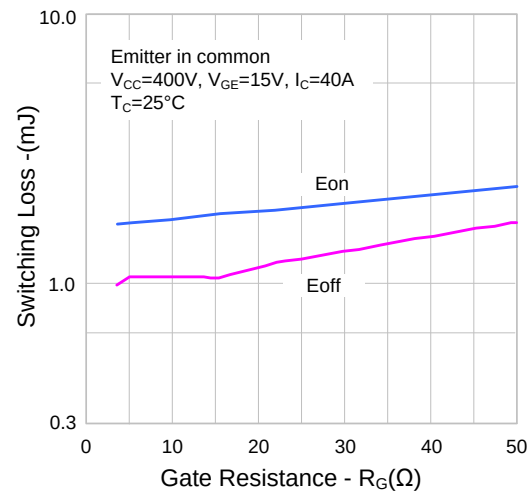
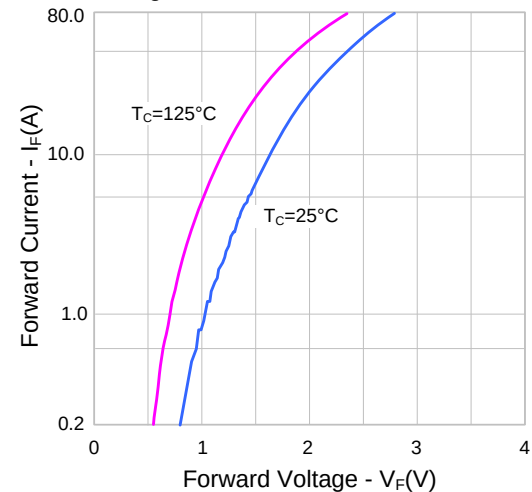
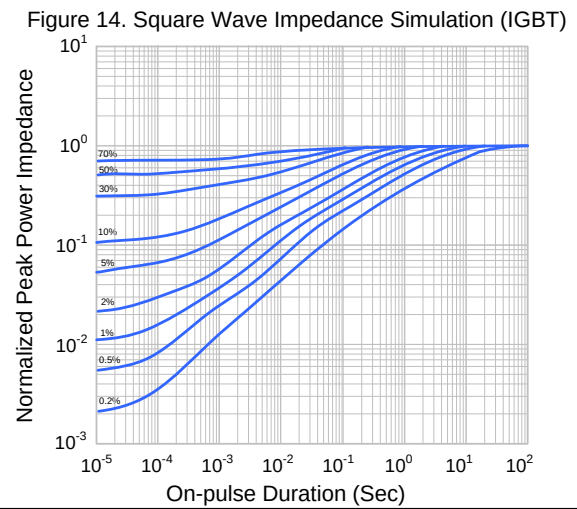
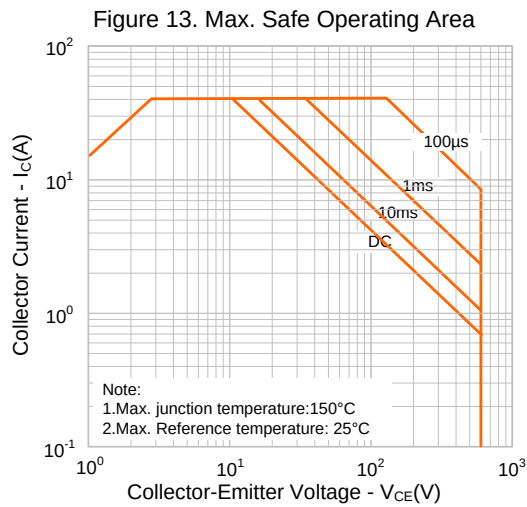


Figure 12. Forward Characteristics





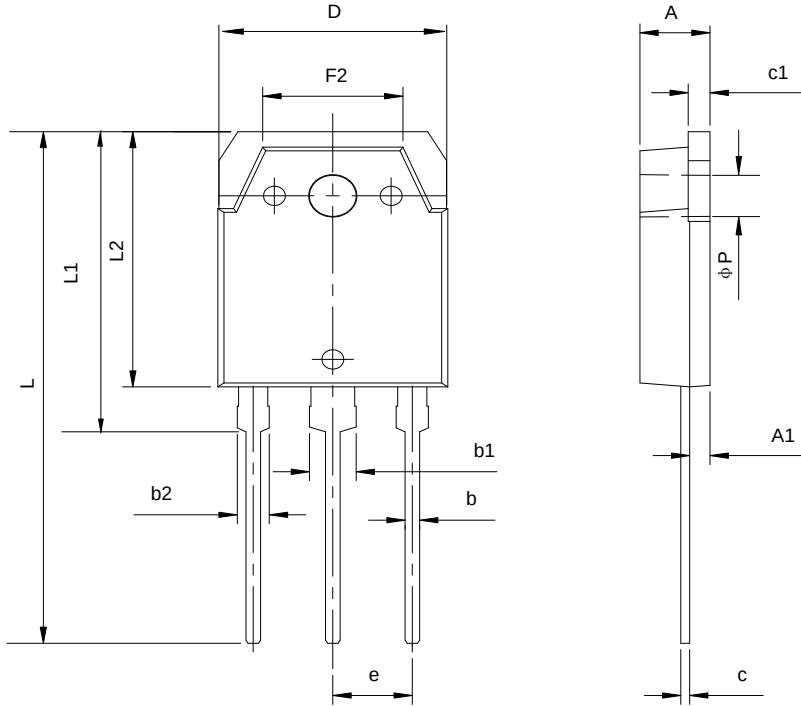
TYPICAL CHARACTERISTIC CURVES(CONTINUED)



PACKAGE OUTLINE

TO-3P

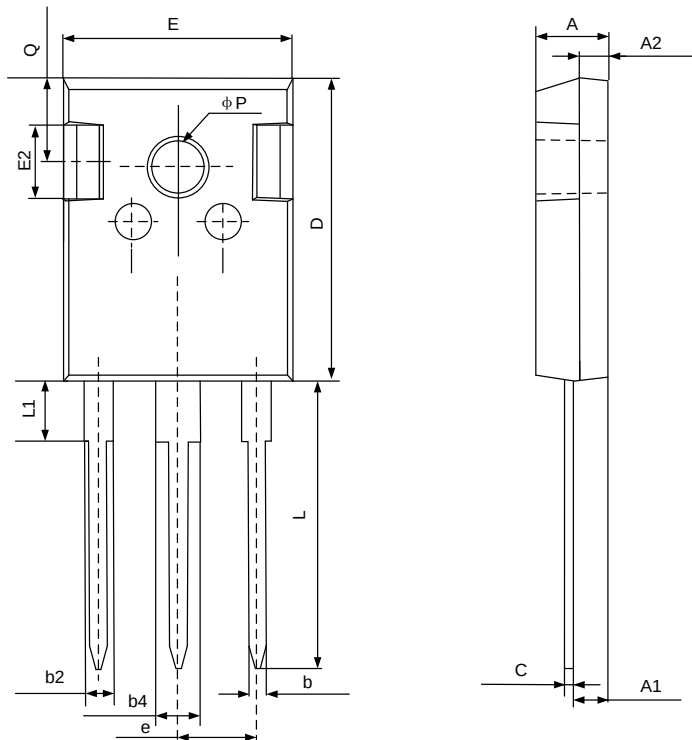
UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.4	—	5.2
c1	1.2	—	1.8
A1	1.2	—	2.0
b	0.7	1.0	1.3
b1	2.7	3.0	3.3
b2	1.7	2.0	2.3
D	15.0	15.5	16.0
c	0.4	0.6	0.8
F2	8.5	—	10.0
e	5.45 TYP		
L1	22.6	—	23.6
L	39.0	—	41.5
L2	19.5	—	21.0
P	3.0	—	3.4

TO-247-3L

UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	—	1.36
b2	1.91	—	2.25
b4	2.91	—	3.25
c	0.51	—	0.75
D	20.80	21.00	21.30
E	15.50	15.80	16.10
E2	4.40	5.00	5.20
e	5.44 BSC		
L	19.72	19.92	20.22
L1	—	—	4.30
Q	5.60	5.80	6.00
P	3.40	—	3.80

PACKAGE OUTLINE(CONTINUED)

TO-3PN

UNIT: mm

The diagram illustrates the mechanical specifications of a TO-3PN package. It includes three views: a top view, a side view, and a detail view of the base. The top view shows a rectangular body with a central circular feature of diameter ΦP . Dimensions include overall width B , mounting hole spacing $B1$, and body width b . The side view shows the package height D , mounting tab thickness A , and base thickness c . The detail view shows the base with mounting holes of diameter e and spacing $b1, b2$. Other dimensions include $A1$ (mounting hole diameter), $A2$ (mounting hole offset), $D1$ (total height), and G (mounting tab height).

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.60	4.80	5.00
A1	1.30	1.50	1.70
A2	2.20	2.40	2.60
b	0.80	1.00	1.20
b1	1.80	2.00	2.20
b2	2.90	3.10	3.30
B	15.20	15.60	16.00
B1	9.10	9.30	9.50
c	0.50	0.60	0.70
D	18.30	18.50	18.70
D1	19.00	19.50	20.00
e	5.25	5.45	5.65
G	2.80	3.00	3.20
ØP	3.00	3.20	3.40

Important notice :

1. The instructions are subject to change without notice!
2. Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current. Please read the instructions carefully before using our products, including the circuit operation precautions.
3. Our products are consumer electronic products or the other civil electronic products.
4. When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.
5. It is strongly recommended to identify the trademark when buying our products. Please contact us if there is any question.
6. Product promotion is endless, our company will wholeheartedly provide customers with better products!
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Rev.: 1.2

Revision History:

1. Add the package outline of TO-3PN
 2. Update the template of datasheet
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Rev.: 1.1

Revision History:

1. Update NOMENCLATURE
 2. Update Marking
 3. Update package outline
-

Rev.: 1.0

Revision History:

1. First release
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